Item		OM for MUC PCB Part Reference	Value	Description	MFG1	MFG1_PN
1	1 1	C1	2.2u	2.2uF 10V X7R 0603 +/-10% -55~125C	muRata	GRM188R71A225KE15D
2	1	C2	10u	CAP,1206,X5R,10uF,+/- 10%, 35V, -55~85C	Taiyo Yuden	GMK316BJ106KL-T
3	1	C3	0.01uF	CAP,0402,X7R,0.01uF,+/- 10%, 35V, 55 85C	muRata	GRM155R71E103KA01D
4	4	C4 C8 C12 C13	0.1uF	CAP,0402,X7R,0.1uF,+/- 10%, 16V, -55~125C	Taiyo Yuden	EMK105B7104KV-F
5	1	C5	2200pF	CAP,0402,X7R,2200pF,+/- 10%, 50V	Yageo	CC0402KRX7R9BB222
6	2	C6 C7	18pF	CAP,0402,NP0,18pF,+/- 5%, 50V	TDK	LMK105BJ224KV-F
7	2	C9 C10	0.22uF	CAP,0402,X7R,0.22uF,+/- 10%, 10V, -55~125C	muRata	GRM155R71H222KA01
8	1	C11	0.47u	CAP CER .47UF 25V X7R 0603	muRata	GRM188R71E474KA12D
9	1	D1	MMSZ5232	ZENER 5.6V 500mW	Diodes	MMSZ5232B-7-F
10	1	D2	LED Green	LED Diffused Green High Efficinecy	Osram	LG L29K-G2J1-24-Z
11	1	D3	RED LED	LED 660NM SUPER RED DIFF 0603SMD	Lumex	SML-LX0603SRW-TR
12	1	FB1	1k/300mA	FER 1K @ 100MHz, 0603 300mA 0.6 Ohm	ТДК	MMZ1608B102C
13	1	J1	MICRO USB-B	CON, USB, Micro, Type B	FCI	10118193-0001LF
14	2	J2 J3	Header 2X8 F	2MM Header Female SMD BOTTOM ENTRY w. Peg, H=2.8MM	Sullins	NPPN082GFNS-RC
15	1	J4	N/L	Heater 7X2,.1X.1, SMD, pin=6.1MM, base-to- pcb=3.56mm	DO NOT	STUFF
16	1	JP2	N/L	Solder Jumper 0201	TBD	TBD
17	2	R1 R2	33	RES,0402,33 OHMS, +/- 5%, 1/16 W	RHOM	MCR01MRTJ330
18	1	R3	1.5k	RES,0402,1.5K OHMS, +/- 5%, 1/16W	Panasonic ECG	ERJ-2GEJ152X
19	1	R4	1M	RES,0402,1M OHMS, +/- 5%, 1/16 W	Panasonic ECG	ERJ-2GEJ105X
20	1	R5	47k	RES,0402,47K OHMS, +/- 5%, 1/16 W	Panasonic ECG	ERJ-2GEJ473X
21	2	R6 R7	1k	RES,0402,1K OHMS, +/- 5%, 1/16 W	Panasonic ECG	ERJ-2GEJ102X
22	2	R8 R19	51	RES,0402,51 OHMS, +/- 5%, 1/16W	Panasonic ECG	ERJ-2GEJ510X
23	2	R9 R10	5.6k	RES,0402,5.6K OHMS, +/- 5%, 1/16W	Stackpole Electronics Inc	RMCF0402JT5K60
24	2	R16 R17	N/L	RES,0402	DO NOT	STUFF
25	1	R20	N/L	RES,0402	DO NOT	STUFF
26	1	U1	LP2985AIM5-3.3	LDO 3.3V 0.15A, VINmax=16V	TI	LP2985AIM5-3.3/NOPB
27	1	U2	TPD4E004	4CH ESD-PROT ARRAY	TI	TPD4E004DRYR
28	1	U3	MSP430F5528IRGCR	MCU 16BIT 128KB FLASH 64VQFN	ТІ	MSP430F5528IRGCR
29	1	U4	LDC1314	INDUCTANCE TO DIGITAL CONVERTER 4CH	ТІ	LDC1314
30	1	U5	40MHz	CMOS,40 MHz,SMD 4pin,1.6-3.3V, 50ppm, 5mA	AVX	KC2520B40.0000C10E00
31	1	Y1	24MHz	CRYSTAL 24.000 MHZ 10PF SMD	СТЅ	403C11A24M00000

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